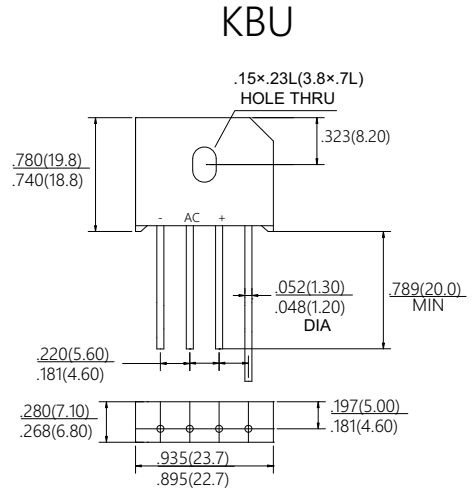


FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junction
- High current capability
- Low forward voltage drop
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Component in accordance to RoHS 2011/65/EU

MECHANICAL DATA

- Case: KBU molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750, method 2026
- Mounting Position: Any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.)

		Symbols	KBU25005	KBU2501	KBU2502	KBU2504	KBU2506	KBU2508	KBU2510	Units
Maximum Recurrent Peak Reverse Voltage		VRRM	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage		VRMS	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage		VDC	50	100	200	400	600	800	1000	Volts
Average Rectified Output Current		Io	25.0							Amp
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)		IFSM	400							Amps
Rating for fusing (t≤8.3ms)		I²t	666							A²s
Maximum Instantaneous Forward Voltage at 12.5 A DC		VF	1.1							Volts
Maximum DC Reverse Current at rated DC blocking voltage	TA=25°C	IR	10							µA
	TA=125°C		500							
Typical thermal resistance		RθJC	1.4 ¹⁾							°C/W
Operating temperature range		TJ	-55 to +150							°C
Storage temperature range		TSTG	-55 to +150							°C

NOTE: 1. Units Mounted on a aluminum plate heat sink.

RATINGS AND CHARACTERISTIC CURVES KBU25005 THRU KBU2510

Characteristics(Typical)

FIG1:Io-Tc Curve

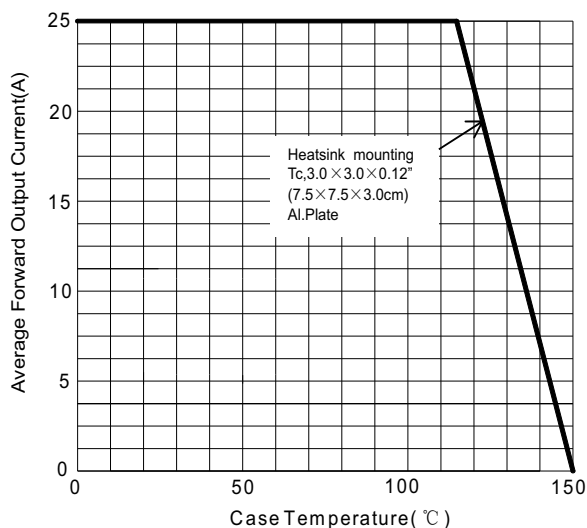


FIG2: Surge Forward Current Capability

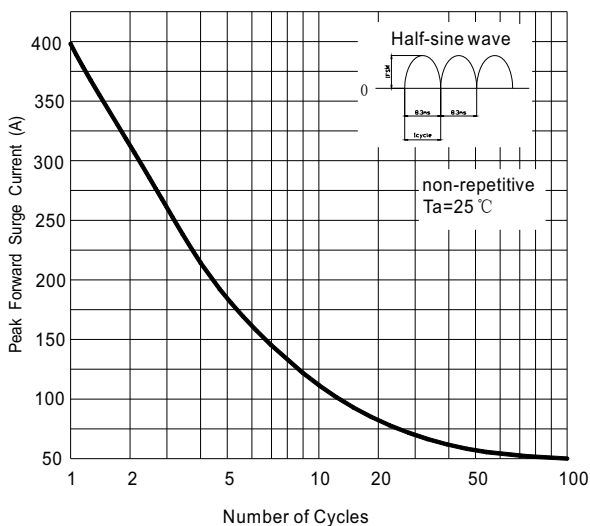


FIG3: Instantaneous Forward Voltage

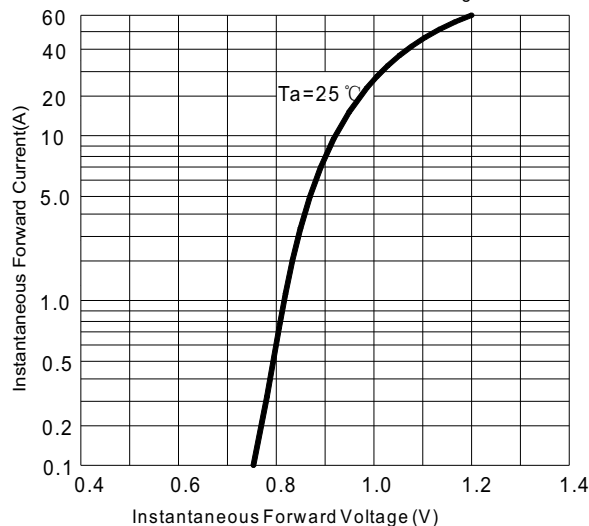


FIG4: Typical Reverse Characteristics

